

Recalibration of MOSFET Compact Models based on Complex Product-Related Layouts using Bayesian Optimization

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IBM Infrastructure

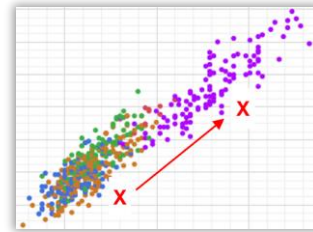
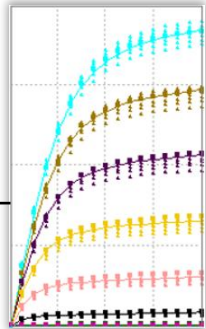


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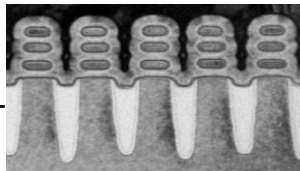
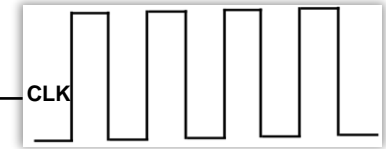


Technology Evolution Drives MOSFETs Model Recalibration

- **Physics-based model equations [1]**
- **Many model parameters**
- **I-V, C-V, noise and RF datasets**
- **Period of weeks to months**



- **Limited model parameters**
- **Discrete parametric targets**
- **Period of days to weeks**



IBM Nanosheet, EE Times 2017

Device fabrication

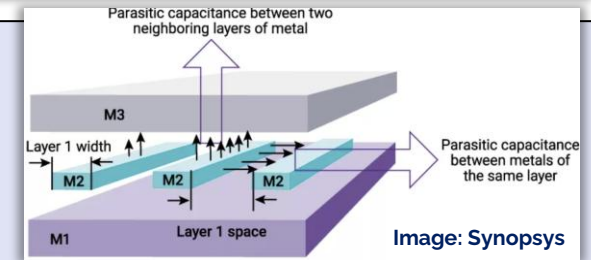
Device Asfit Modeling

Device model recalibration

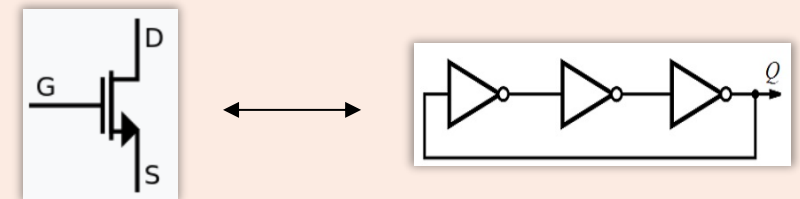
Circuit SPICE simulation

Technology Scaling Challenges Model Recalibration

- Challenges to accurate MOSFET modeling arise from:
 - Increasing wiring parasitic.
 - Increasing Local Layout Effect (LLE).
 - Increasing SPICE simulation time from accurate Parasitic Extraction (**PEX**) netlists



- Discrepancy between ***product circuit*** measurement and SPICE simulation, which is based on ***single device*** extrapolated compact model:
 - operating under different PVT conditions.
 - surrounded with different layout environments.
 - optimized with different performance targets.



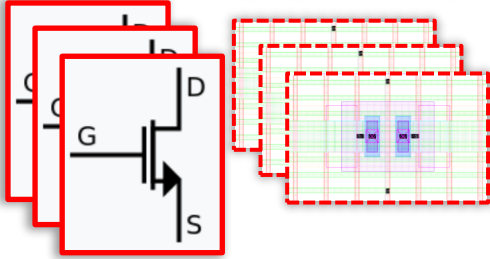
Most prior arts only support device-level model recalibration based on simplified pre-layout schematic netlist [2][3].

[2] Sachin Bhat, *et al.*, “Compact Model Parameter Extraction using Bayesian Machine Learning,” IEEE Computer Society Annual Symposium on VLSI, 2023

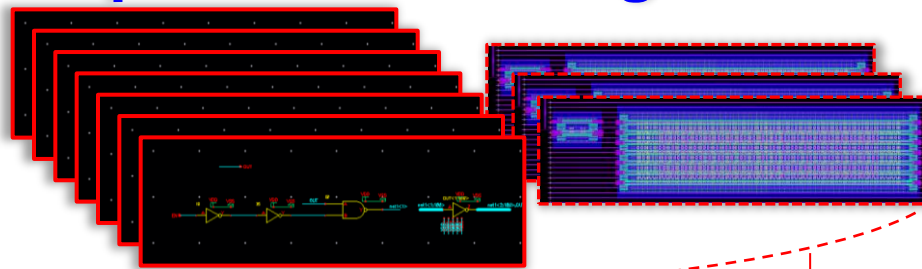
[3] Jeessoo Chang, *et al.*, “A Systematic Compact Model Parameter Calibration with Adaptive Pattern Search Algorithm,” Applied Sciences (2076-3417), 2021, Vol 11, Issue 9, p4155

Main idea #1: Multiple Product-Related Layouts Driven Recalibration

MOSFETs



Multiple benchmarking circuits



**FET PEX-netlist
DC simulation**

**RO PEX-netlist
transient simulation**

**Process Design
Kit (PDK)
Compact model**

- ***Multiple*** product performance benchmarking circuits are included to drive model recalibration.
 - Ring oscillator (RO) ↔ combinational logic circuit
 - LATCH ↔ sequential logic circuit
 - SRAM ↔ array structures
 - current mirror ↔ analog module
- ***PEX***-netlists based SPICE simulation for both benchmarking circuits and devices.

Multi-circuit optimization problem!

Main idea #2: In-Parallel Multi-Circuit Bayesian Optimization

A parallel Bayesian optimization algorithm and associated software infrastructure to solve multi-circuit optimization.

1. *Input-to-Netlist Parameter Mapper*

- Maps one or more “optimization parameters” to one or more “netlist parameters”
- Defines bounds, step size, constraints

2. *Cluster Broker*

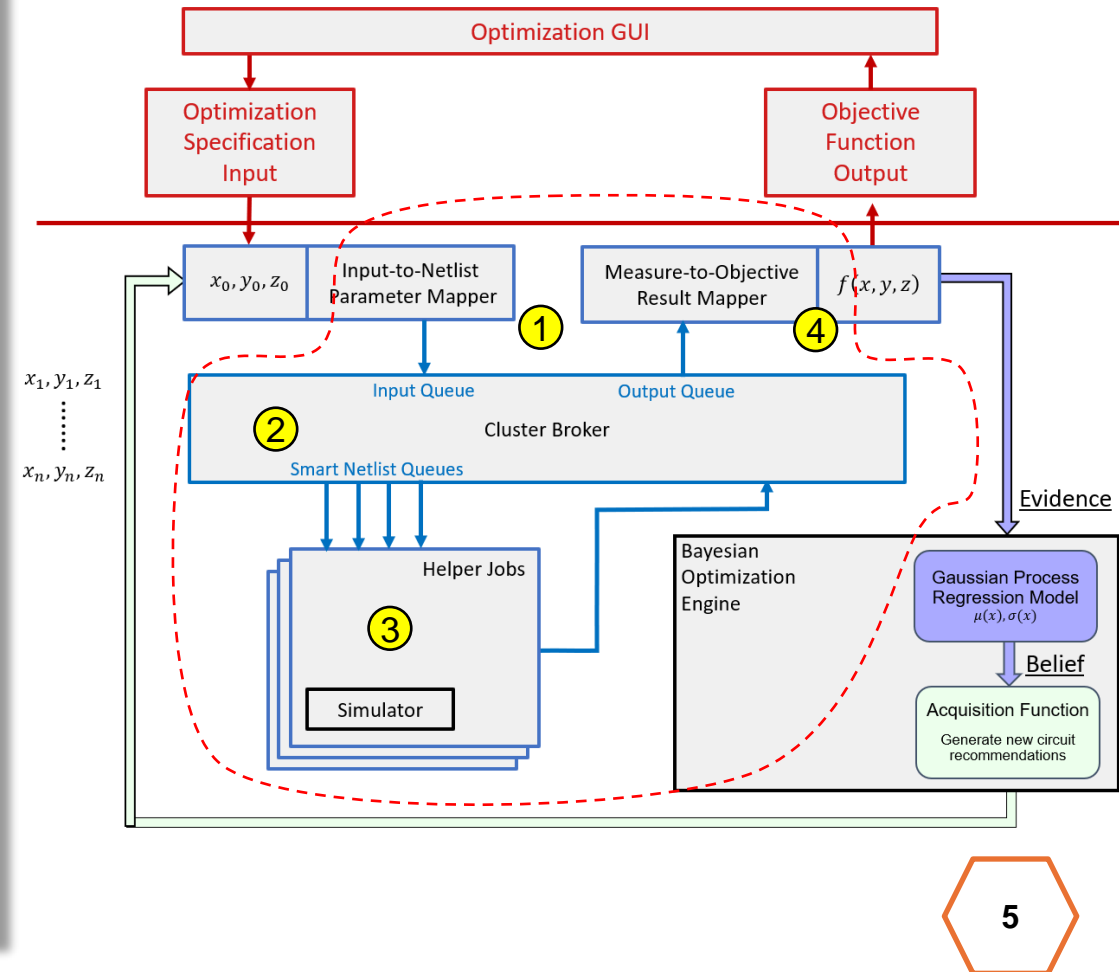
- Launches multiple simulator “helper” jobs
- Maintains smart queues to maximize the parallelism

3. *Helper Jobs*

- Can rerun existing simulation with new optimization parameters
- Restart simulation on different netlist if required

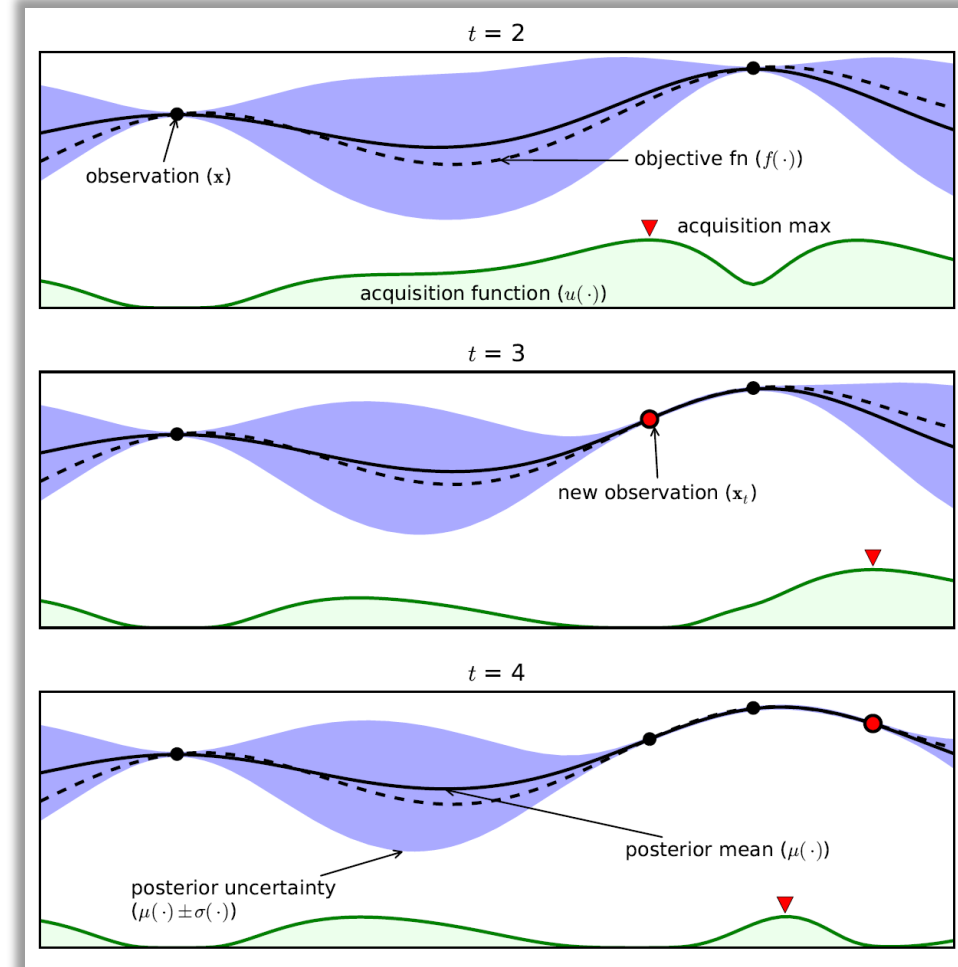
4. *Measure-to-Objective Result Mapper*

- Collects outputs from individual simulation and constructs objective function



Why Choose Bayesian Optimization

- Bayesian Optimization is an efficient global optimization strategy for:
 - **expensive black box function**: multi-circuit PEX netlist SPICE simulations.
 - **optimization with a limited optimization parameters**: limited model parameters for recalibration.
 - **searching the global min/max for objective function**: SPICE simulation vs. hardware targets.
- Two Key Components:
 - **Surrogate Function**: Statistical model built from a Gaussian Process Regression using the training data.
 - **Acquisition Function**: Function to determine next position to sample.

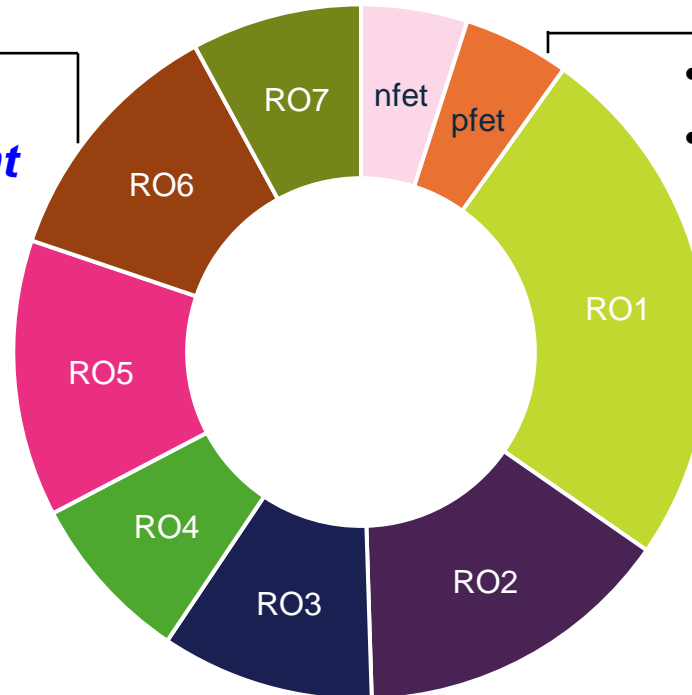
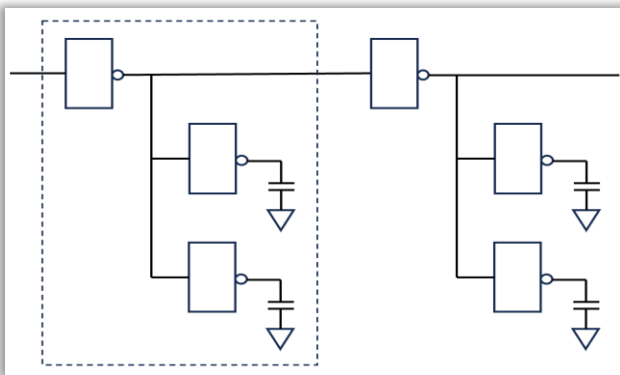


[4] E. Brochu, *et al.* "A tutorial on Bayesian optimization of expensive cost functions, with application to active user modeling and hierarchical reinforcement learning," *arXiv:1012.2599*, 2010.

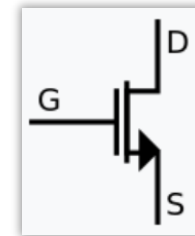
A Practical Example

- ❑ A MOSFET model recalibration based on a multi-Vt FinFET technology.
- ❑ Model recalibration combining DC analysis on *single transistor devices* (n and p) and transient analysis on *multiple ring oscillator (RO) circuits*.
 - ❑ 101-stage RO
 - ❑ Different NOT gate type: INV, NAND, NOR, ...

- PVT: product use corners
- Circuit analyses: *multiple transient simulation netlist*



- PVT: nominal corner
- Circuit analyses: *one DC simulation netlist*



Practical Example Continues

How to formulate objective function?

- Evaluation metrics are the combination of 7 ROs and 2 FETs.
 - MOSFET: threshold voltage V_t and effective current I_{eff}
 - RO: *frequency*
- A “global” RO is defined to represent the overall performance of multiple ROs.
 - $W1_j$: weight factor for each RO
 - $Freq_j$: frequency metric of each RO
$$RO_Freq_g = \sum_{j=1}^7 W1_j * Freq_j$$
- Normalized unitless error “ Err_i ” is defined for each individual metric
 - opt_i : recalibrated model simulation result
 - tgt_i : target extracted from hardware measurement
- Total **fitness error score** is the sum of normalized unitless errors.
 - $W2_i$: weight factor of individual metric (frequency/ V_t / I_{eff})

$$Err_i = \frac{(opt_i - tgt_i)^2}{tgt_i^2}$$

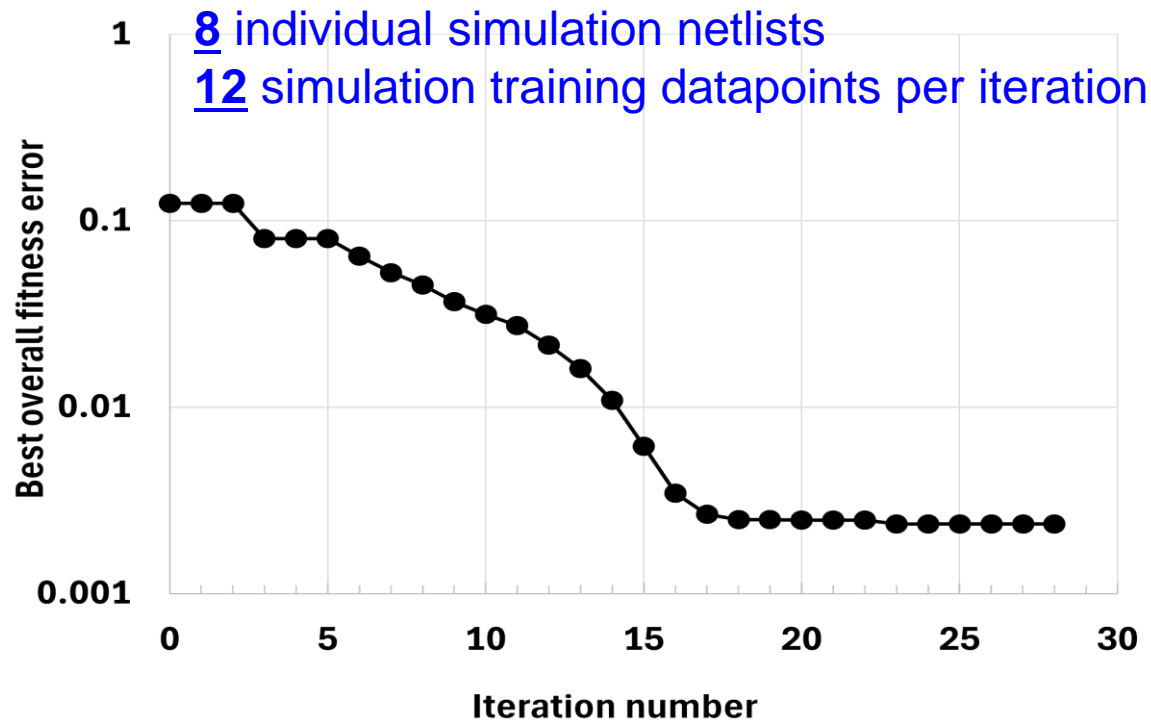


$$Fitness_err = \sum_{i=1}^N W2_i * Err_i$$

❑ ~10 BSIM-CMG model parameters selected:

- Work function parameters
- Mobility parameters
- Capacitance parameters
- Local layout effect parameters

Results



	Manual recalibration	Auto-recalibration
Metrics	Model vs. target	Model vs. target
Vt (NFET)	-1.71 mV	-0.12 mV
Ieff (NFET)	2.10%	-0.76%
Vt (PFET)	0.57 mV	-0.09 mV
Ieff (PFET)	2.38%	0.20%
Freq (RO1)	2.39%	0.05%
Freq (RO2)	-5.66%	-3.72%
Freq (RO3)	-2.37%	-0.33%
Freq (RO4)	-3.48%	-0.70%
Freq (RO5)	1.17%	3.98%
Freq (RO6)	1.55%	-0.43%
Freq (RO7)	3.40%	1.38%
RO_Freq_g	0.53%	0.03%
Time	~ 1 human week	~ 32 machine hrs.

- ❑ 96 simulations per iteration distributed in 24 machines in-parallel .
- ❑ Best score found in iteration #23 with total 288 (=24*12) training datapoints.
- ❑ Total turnaround time is ~ 32 hours.

- ❑ The turnaround time of manual recalibration is very dependent on the skill of the model engineer.
- ❑ With our multi-design circuit Bayesian optimization infrastructure, turn-around-time has been reduced from weeks to days or hours with better model quality.

Summary

- **Improved accuracy** through MOSFET model recalibration:
 - Leveraging **multiple product-related circuits** to drive model recalibration.
 - Including **Parasitic EXtraction netlist** in SPICE simulation.
- **Enhanced efficiency** of MOSFET model recalibration:
 - utilizing **Bayesian optimization** algorithm.
 - developing **multi-circuit optimization** infrastructure.
- Demonstrated reduction of turn-around-time from weeks to days with better model quality.